

## **PRESS RELEASE:**

### **RTI introduces the first truly flexible QFN Socket for FA and Engineering / Production**

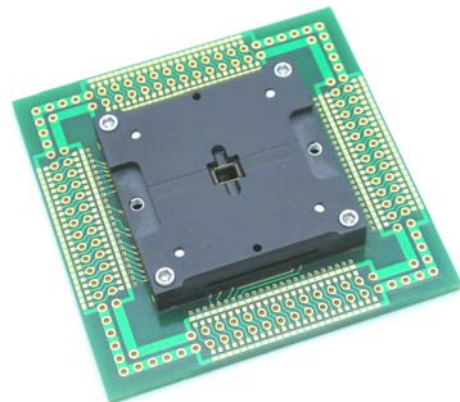


The RTI 900-113X pogo pin sockets are designed to meet most low pin count failure analysis and engineering test requirements for QFN, LLP, QFP, BGA, LGA, LLP and other types of small packages. Several lid styles are available including a screw-down FA lid for micro-probing, a dual-latch lid and dual-latch clam-shell lid for engineering, and several other special purpose lids.

The sockets are designed for bench test, liquid crystal analysis, ESD testing, back-side emission, micro probing, characterization, and low volume engineering and production testing. Options include multiple center ground pads and heated sockets for liquid crystal testing. Mini-DUT cards and many types of fixtures are available for almost any type of FA, engineering, or production application. The 900-113X sockets are priced midway between burn-in sockets and full production sockets.

#### **Features:**

- Package sizes from 1mm to 12 mm
- Pitches: 0.4mm and larger
- Custom pad configurations
- Multiple lid styles available to meet almost any application
- Optional pockets for components under the socket
- Optional center ground pins
- Optional hole through socket for back side test
- Multiple pin styles available for lead-free and RF applications
- Compatible DUT cards available



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NOTE: Top picture is robson63.jpg (lightened)  
Bottom picture: Mini card with 900-1130 socket 726.jpg